

High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1187-ND

ATS PART # ATS-53310R-C2-R0

Features & Benefits

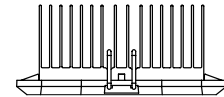
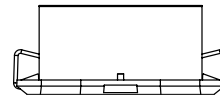
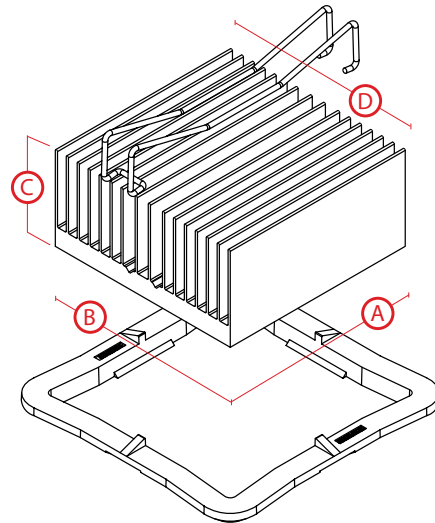
High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Designed specifically for BGAs and other surface mount packages

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material



Thermal Performance Table

| AIR VELOCITY | | THERMAL RESISTANCE | |
|--------------|-----|--------------------|---------------|
| FT/MIN | M/S | °C/W (UNDUCTED) | °C/W (DUCTED) |
| 200 | 1.0 | 4.7 | 3.1 |
| 300 | 1.5 | 3.8 | |
| 400 | 2.0 | 3.3 | |
| 500 | 2.5 | 2.9 | |
| 600 | 3.0 | 2.7 | |
| 700 | 3.5 | 2.5 | |
| 800 | 4.0 | 2.4 | |

Product Details†

| DIMENSION A | DIMENSION B | DIMENSION C§ | DIMENSION D | TIM† | FINISH |
|-------------|-------------|--------------|-------------|--------|----------------|
| 31 | 31 | 19.5 | N/A | C1100F | BLACK-ANODIZED |

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

† TIM = Thermal Interface Material

‡ Dimensions are measured in millimeters

♦ Dimensions A & B refer to component size

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



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